

1-2405

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Form PTO-1595 (Rev. 06/04)  
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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)/Execution Date(s):**

Susheel G. Jadhav; Daoqiang Lu

Execution Date(s) 12/15/04; 12/31/04

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No**3. Nature of conveyance:**

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other \_\_\_\_\_

**2. Name and address of receiving party(ies)**

Name: Intel Corporation

Internal Address: \_\_\_\_\_

Street Address: 2200 Mission College Boulevard

City: Santa Clara

State: California

Country: USA Zip: 95052

Additional name(s) & address(es) attached? ☐ Yes ☒ No**4. Application or patent number(s):**

A. Patent Application No.(s)

10/948,266

☐ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Kerry D. Tweet

Internal Address: M/S SC4-202

Street Address: P.O. Box 5326

City: Santa Clara

State: California Zip: 95056-5326

Phone Number: 503-712-3206

Fax Number: 503-264-1729

Email Address: kerry.d.tweet@intel.com

**6. Total number of applications and patents involved:**

1

**7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00**

- ☐ Authorized to be charged by credit card  
☒ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

**8. Payment Information**a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_

b. Deposit Account Number 50-0221

Authorized User Name Kerry D. Tweet

**9. Signature:**

Signature

Date

Kerry D. Tweet, reg. No. 45,959

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

5

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

01/26/2005 ECOOPER 00000316 500221 10948266

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PATENT  
REEL: 016179 FRAME: 0717

Attn: Derek Watson

Applicant's Reference No.: P20024

**ASSIGNMENT**

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned:

**Susheel G. Jadhav; Daoqiang Lu**

hereby sell, assign, and transfer to:

**Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052-8119 USA ("Assignee"), and it's successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to, any and all inventions and improvement that are disclosed in the application for the United States patent filed on September 22, 2004, and assigned Application No. 10/948,266 and is entitled:

**Method for Attaching a Semiconductor Die to a Substrate and Heat Spreader**

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvement; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority from the filing of said United States application;

agree that said Assignee may apply for and receive a patent for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, it successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, it successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, it successors, assigns, and legal representatives in securing and maintaining proper patent protections for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

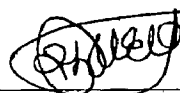
covenant with said Assignee, it successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Attn: Derrek Watson

**Each Inventor: Please Sign and Date Below:**

12-31-04

Date



Name: **Susheel G. Jadhav**

                      
Date

                      
Name: **Daoqiang Lu**

Applicant's Reference No.: P20024

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### **Method for Attaching a Semiconductor Die to a Substrate and Heat Spreader**

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvement; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority from the filing of said United States application;

agree that said Assignee may apply for and receive a patent for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, and legal representatives in securing and maintaining proper patent protections for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor: Please Sign and Date Below:

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\_\_\_\_\_  
Date

\_\_\_\_\_  
Name: **Susheel G. Jadhav**

12/15/2004  
Date

  
\_\_\_\_\_  
Name: **Daoqiang Lu**